

7/B
w/ Drawing 6/26/03
END919970013US2
Mallini

Appln. No. 10/001,421
Amendment Dated June 17, 2003
Reply to Office Action of May 21, 2003



Appln. No:
Applicants:
Filed:
Title:
TC/A.U.:
Examiner:
Confirmation No.:
Docket No.:

10/001,421
Joseph M. Milewski et al.
November 2, 2001
LOW TEMPERATURE SOLDER CHIP ATTACH STRUCTURE
2811
Hung K. Vu
4204
END919970013US2

AMENDMENT

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Responsive to the Office Action dated May 21, 2003, please amend the above-identified application as follows:

- ☒ **Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.
- ☒ **Amendments to the Drawings** begin on page 3 of this paper and include an attached replacement sheet.
- ☒ **Remarks/Arguments** begin on page 4 of this paper.

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